Abstract of the Disclosure:

A process tool, preferably a spin coater, includes a set of at least three arms and an adjustable rinse nozzle. The arms lift a substrate, e.g. a semiconductor wafer, from a chuck inside the process chamber after having performed the corresponding manufacturing step, e.g. coating. The contact area between the arms and the substrate is as small as possible. The rinse nozzle dispenses a solvent liquid onto the backside of the substrate, thereby removing contaminating particles located at the area of contact between the vacuum channels of the chuck and the substrate. The set of arms rotates for a homogeneous cleaning. A gas flowing out of vacuum ports of the chuck prevents the vacuum ports from being obstructed with particles. While the substrate is being lifted, the chuck can also be cleaned by dispensing the solvent liquid onto the chuck.

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